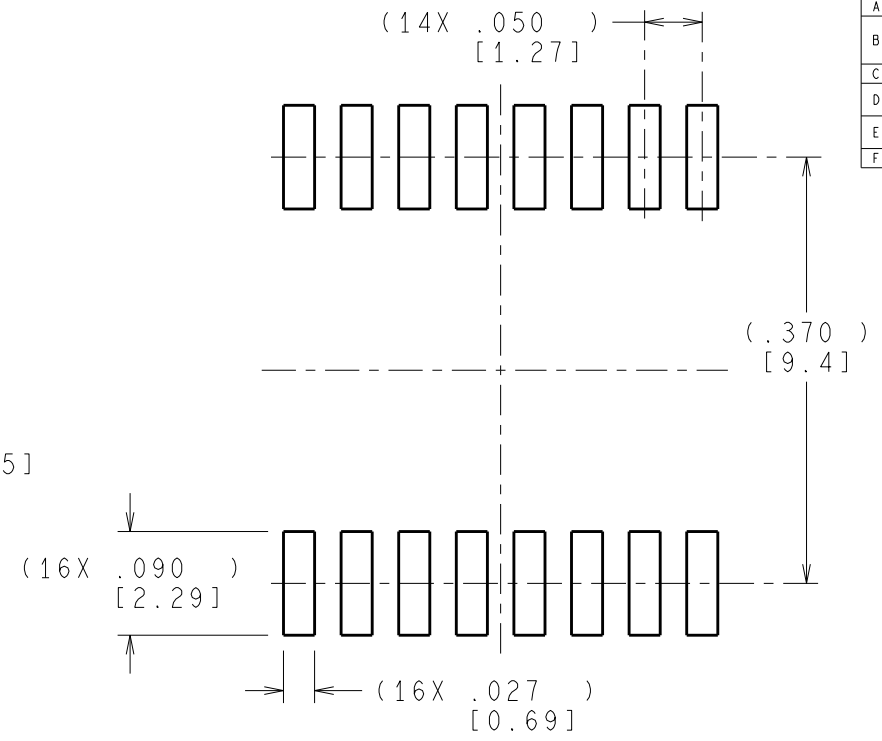
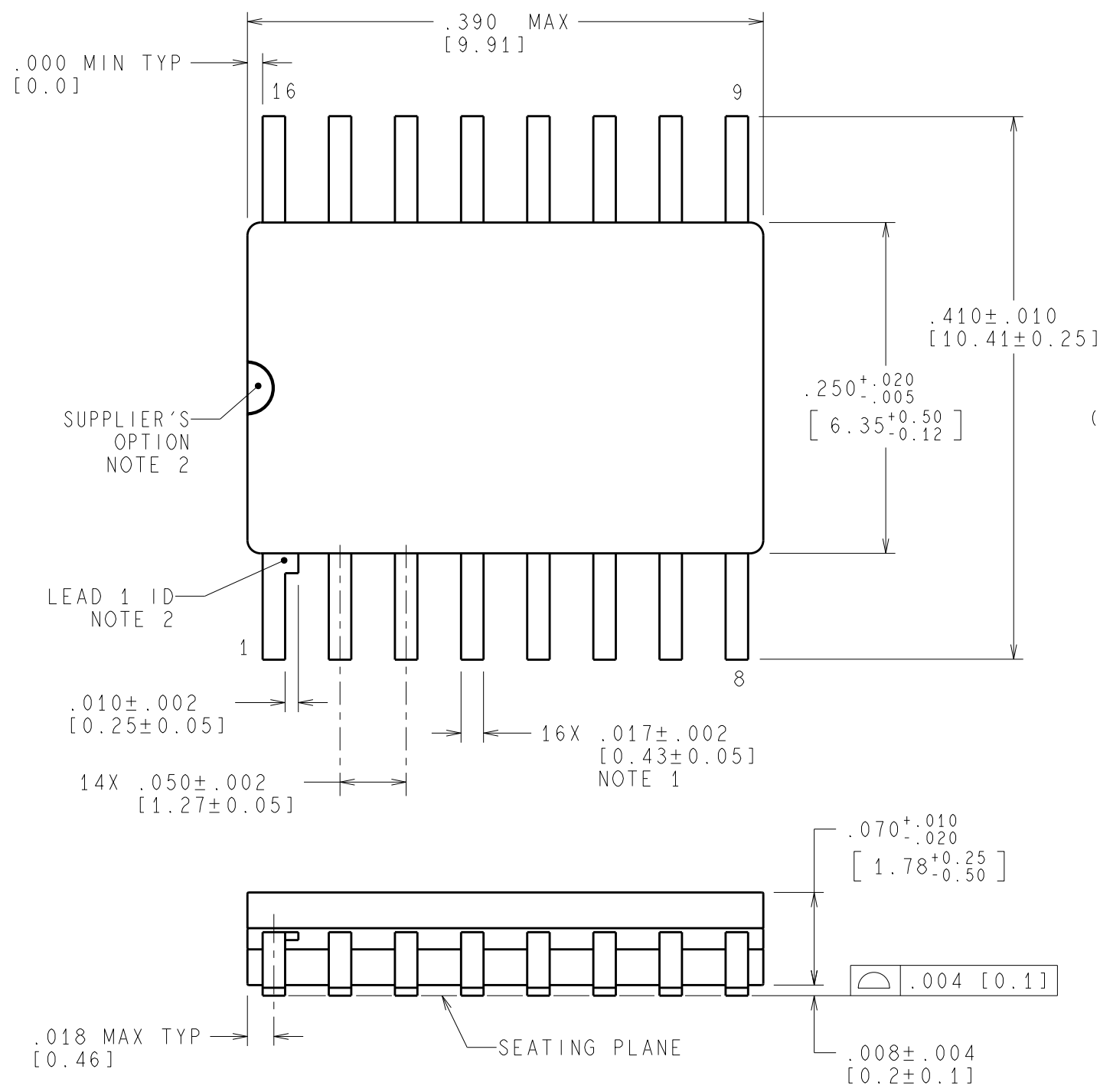
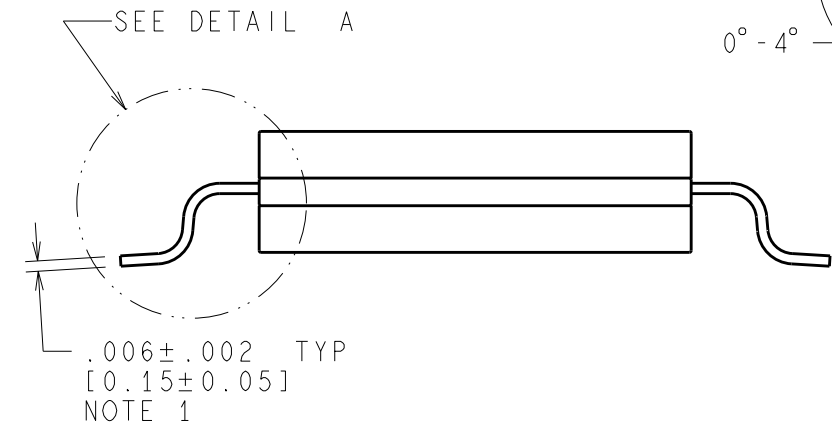
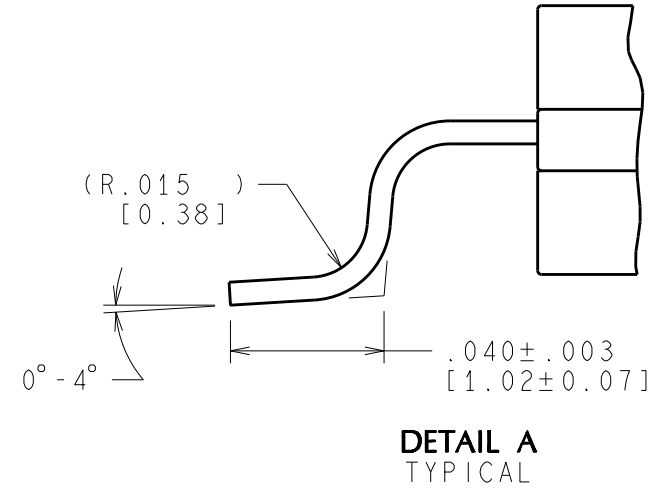


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11376	02/29/1996	MS/KH
B	LD PITCH TOL WAS ±.005; CHANGE LD RADIUS TO REF DIM; REMOVE THE OTHER R.006±.002; DIM .040±.003 WAS .037±.003	11443	04/19/1996	MS/KH
C	R .015[0.38] WAS R .006[0.15]	11840	10/08/1997	TL/KH
D	.000 MIN WAS .005 MIN; UPDATE TITLE; CHANGE TO B SIZE FORMAT	1535	07/13/2004	TL/CBS
E	ADD RECOMMENDED LAND PATTERN; UPDATE NOTE 3; REVISE DWG TITLE.	2365	07/27/2007	MS/JL
F	ADD LEAD DETAIL A FOR CLARITY; UPDATE NOTE 1	13935	06/23/2011	TL/JL



RECOMMENDED LAND PATTERN



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- LEAD 1 IDENTIFICATION SHALL BE:
 - A NOTCH OR OTHER MARK WITHIN THIS AREA.
 - A TAB ON LEAD 1, EITHER SIDE.
- NO JEDEC REGISTRATION AS OF JUNE 2011.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS
 DIMENSIONS IN () FOR REFERENCE ONLY

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS	DATE	National Semiconductor	
DRAWN MARTA SUCHY	02/29/1996	2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DFTG. CHK. THANH LEQUANG	06/23/2011	CERPACK, .390x.250x.070in, 16 LD, .050in PITCH, GULL WING	
ENGR. CHK. JOE LUNDY	06/23/2011		
PROJECTION	SCALE	SIZE	DRAWING NUMBER
	NTS	B	(SC)MKT-WG16A
FORMERLY: N/A	SHEET 1 of 1		REV F